LISTING OF CLAIMS:

These claims will replace all prior versions of claims in the present application.

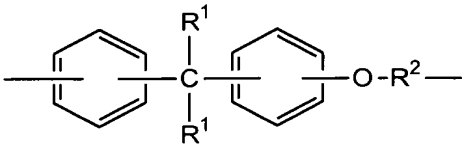
1. (Original) A photosensitive resin composition, comprising:

(A) a polymer having a carbon-carbon double bond and carboxyl group, formed by the reaction of an acid anhydride with the reaction product of an epoxy compound having a repeating unit expressed by the following general formula (1a) and a repeating unit expressed by the following general formula (1b) with an unsaturated carboxyl compound having a carbon-carbon double bond and a carboxyl group,

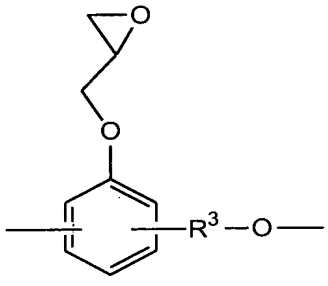
(B) a photopolymerizable monomer,

(C) a radical photopolymerization initiator, and

(D) a curing agent having reactivity with a functional group of said polymer and/or said photopolymerizable monomer:



· · · (1a)

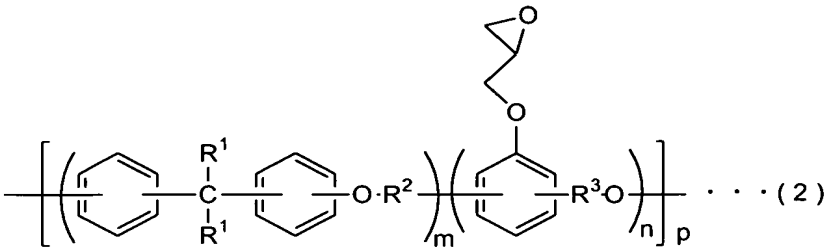


· · · (1b)

[in the formula, R^1 is a hydrogen atom or methyl group, R^2, R^3 are alkylene

groups].

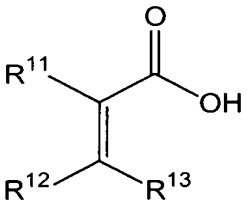
2. (Original) The photosensitive resin composition according to Claim 1, wherein said epoxy compound is an epoxy compound expressed by the following general formula (2):



· · · (2)

[in the formula, R^1 is a hydrogen atom or methyl group, R^2, R^3 are alkylene groups, m, n are positive integers such that m+n=2-50, and p is a positive integer].

3. (Currently Amended) The photosensitive resin composition according to Claim 1 ~~or 2~~, wherein said unsaturated carboxyl compound is a compound expressed by the following general formula (3):



· · · (3)

[in the formula, R^{11} is a hydrogen atom or alkyl group, and R^{12}, R^{13} are independently a hydrogen atom, alkyl group, aryl group, styryl group, furfuryl group or cyano group].

4. (Currently Amended) The photosensitive resin composition according to ~~any one of Claims 1-3~~ Claim 1, wherein said unsaturated carboxyl compound is (meth)acrylic acid.

5. (Currently Amended) The photosensitive resin composition according to Claim 1 ~~or 2~~, wherein said unsaturated carboxyl compound is a monoester of a dibasic acid having a carbon-carbon double bond.

6. (Original) The photosensitive resin composition according to Claim 5, wherein said monoester is a monoester obtained by reacting an acid anhydride with a (meth)acrylate compound having a hydroxyl group.

7. (Currently Amended) The photosensitive resin composition according to ~~any one of Claims 1-6~~ Claim 1, further containing an elastomer.

8. (Currently Amended) The photosensitive resin composition according to ~~any one of Claims 1-7~~ Claim 1, further containing a phenoxy resin.

9. (Currently Amended) The photosensitive resin composition according to ~~any one of Claims 1-8~~ Claim 1, further containing a block isocyanate.

10. (Currently Amended) The photosensitive resin composition according to ~~any one of Claims 1-9~~ Claim 1, further containing a non-elastomer-like polymer of a polymerizable compound having a carbon-carbon double bond.

11. (Currently Amended) A photosensitive element comprising a support, and a photosensitive resin composition layer composed of the photosensitive resin composition according to ~~any one of Claims 1-10~~ Claim 1

formed on said support.

12. (Currently Amended) A method of forming a resist pattern, comprising the steps of:

laminating a photosensitive resin composition layer of the photosensitive resin composition according to ~~any of Claims 1-10~~ Claim 1 so as to cover a conductive layer, on an insulating substrate of a laminated substrate comprising said insulating substrate and said conductive layer having a circuit pattern formed on said insulating substrate,

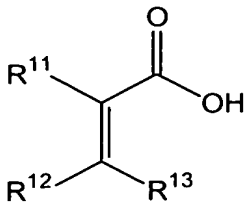
forming an exposed part by irradiating a predetermined part of said photosensitive resin composition layer with an activation light, and

removing parts except said exposed part in said photosensitive resin composition layer.

13. (Currently Amended) A printed circuit board, comprising an insulating substrate, a conductive layer having a circuit pattern formed on said insulating substrate and a resist layer formed on said insulating substrate so as to cover said conductive layer, wherein:

said resist layer is the cured product of the photosensitive resin composition according to ~~any of Claims 1-10~~ Claim 1, and said resist layer has an opening so that at least part of said conductive layer is exposed.

14. (New) The photosensitive resin composition according to Claim 2, wherein said unsaturated carboxyl compound is a compound expressed by the following general formula (3):



· · · (3)

[in the formula, R^{11} is a hydrogen atom or alkyl group, and R^{12}, R^{13} are independently a hydrogen atom, alkyl group, aryl group, styryl group, furfuryl group or cyano group].

15. (New) The photosensitive resin composition according to Claim 2, wherein said unsaturated carboxyl compound is (meth)acrylic acid.

16. (New) The photosensitive resin composition according to Claim 3, wherein said unsaturated carboxyl compound is (meth)acrylic acid.

17. (New) The photosensitive resin composition according to Claim 2, wherein said unsaturated carboxyl compound is a monoester of a dibasic acid having a carbon-carbon double bond.